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Product Change Notification - JAON-26SYMB368 (Printer Friendly)

Date: 13 Oct 2015
Notification subject: CCB 1725 Initial Notice: Qualification of 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site.

Notification text: **PCN Status:** Initial notification
Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.
NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).
Description of Change: Qualification of 8390A die attach material for products available 18L SOIC package using palladium coated copper wire (PdCu) bond wire at MTAI assembly site

Pre Change: 3280 die attach material
Post Change: 3280 die attach material or 8390A die attach material

Impacts to Data Sheet: None
Reason for Change: To improve on-time delivery performance by qualifying 8390A die attach material.

Change Implementation Status: In Progress
Estimated First Ship Date: October 30, 2015 (date code: 1544)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.
Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History: **October 13, 2015:** Issued initial notification.
The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-26SYMB368_Qual_Plan.pdf](#)
[PCN_JAON-26SYMB368_Affected_CPN.pdf](#)
[PCN_JAON-26SYMB368_Affected_CPN.xls](#)

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